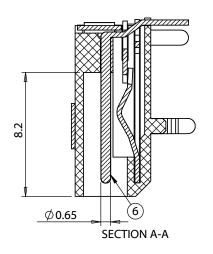
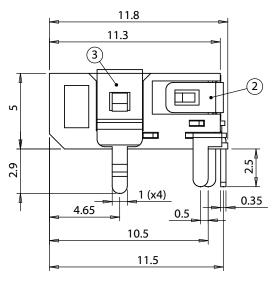
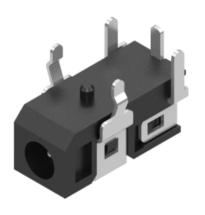


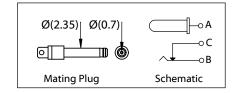
0.3 (x2)

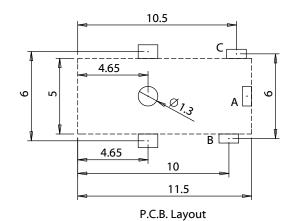
0.26 (x2)











Revision:	Date:	Description:	Prepared:	Notes:						
Α	9/26/2018	Initial release		Function test: no open, no short	t circuit, no			VISII -	ITY	
			Verified:	intermittent						
							tel 1.541.323.3228 800 877.670 fax 1.541.323.4202 web tensility.			
			Dimensions are in			iux 1.541.525.4202 web terisiiity.com				
			millimeters.	Description: Connector, dc jack 2.35x0.7 mm, PCB mount, 90°, silver plated, board lock		Size: Part number:				
			Tolerances: \leq 1.0: \pm 0.1 mm			Α	54-00	-00139		
			1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm			Scale:	4:1		Sheet 1 of 2	
		A								

5 3 2

Ratings

Maximum operating voltage: 48 V

Maximum operating current: 5.0 A (not mated under load)

Operating Temperature Range

-25 to 85 °C, relative humidity of 85% or less

Materials

1)Insulator: PBT, black

(2)Cover: brass, nickel plated

(3)Terminal: brass, tin plated

(4)Terminal: brass, silver plated

(5)Terminal: beryllium copper, silver plated

(6)Center Pin: brass, silver plated

Electrical Requirements

Dielectric strength: 1 min @ 500 Vac

Insulation resistance: 100 MΩ @ 500 Vdc minimum

Contact resistance: $50 \text{ m}\Omega$ maximum

Mechanical Requirements

Insertion force: 0.4-0.9 kgf

Withdrawal force: 0.3-0.7 kgf

Life cycle: 5000 mating cycles while maintaining contact resistance: $100 \text{ m}\Omega$ maximum, withstand voltage: 250 Vac, 1 min

Terminal strength: 300 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and without damage or excessive looseness of terminals

Soldering

Solderability: 75% minimum coverage when terminals dipped 2mm in 245 \pm 5 °C solder bath for 3 \pm 0.5 seconds

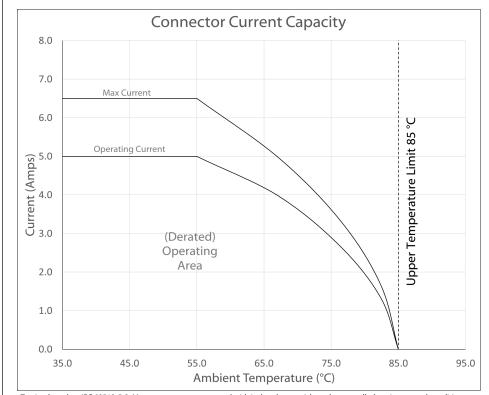
Solder bath durability: no deformation when immersed in 255 \pm 5 °C up to surface of the board 1.6 mm for 5 seconds or less

Solder iron durability: no deformation when exposed to 350 \pm 10 $^{\circ}$ C for 3 \pm 0.5 seconds

Environmental Requirements

Cold test: -25 ± 3 °C for 48 hours without deformation Heat test: 85 ± 2 °C, relative humidity 45-85% for 48 hours without deformation

Humidity test: 40 ±2 °C, relative humidity 90-95% for 48 hours without deformation



Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings, mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation.

Wave Soldering Temperature Profile

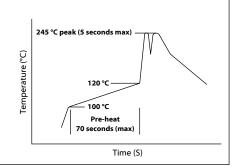
Pb - Free Flow Profile

Solder temperature: 245 °C

Time: 5 seconds maximum Pre-heat: 100 ~120°C

Time: 70 seconds maximum

Measure point: surface of the solder leads



Revision:	Date:	Description:	Prepared:	Notes:				
Α	9/26/2018	Initial release		Function test: no open, no short circuit, no intermittent		\vdash	JISI	ITY
			Verified: Dimensions are in millimeters. Tolerances: < 1.0: ± 0.1 mm 1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm			tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com		
				Description: Connector, dc jack 2.35x0.7 mm, PCB mount, 90°, silver plated, board lock	Size:	Part nur 54-00		
					Scale:	5:1		Sheet 2 of 2

3 2